

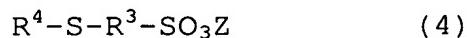
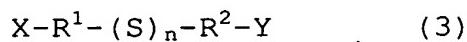
Amendments to the Claims

This listing of claims will replace all prior listings of claims in the application.

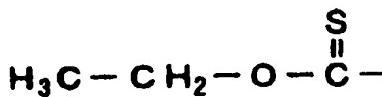
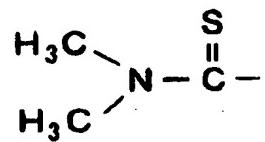
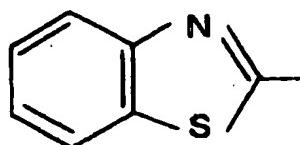
Listing of Claims

1.-3. (Canceled)

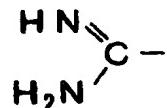
4. (Currently Amended) The copper electrolytic solution according to ~~Claim 1~~Claim 7, wherein the organic sulfur compound is expressed by the following General Formula (3) or (4):



~~in, in~~ General Formulas (3) and (4),  $R^1$ ,  $R^2$ , and  $R^3$  are each an alkylene group with 1 to 8 carbon atoms,  $R^4$  is selected from the group consisting of hydrogen,



and



$X$  is selected from the group consisting of hydrogen, a sulfonic acid group, a phosphonic acid group, and an alkali metal salt or ammonium base of sulfonic acid or phosphonic acid,  $Y$  is selected from the group consisting of a sulfonic acid group, a phosphonic acid group, and an alkali metal salt of sulfonic acid or phosphonic acid,  $Z$  is hydrogen or an alkali metal, and  $n$  is 2 or ~~3~~or 3.

5. (Currently Amended) An electrolytic copper foil produced using the copper electrolytic solution according to ~~Claim 1~~ Claim 7.

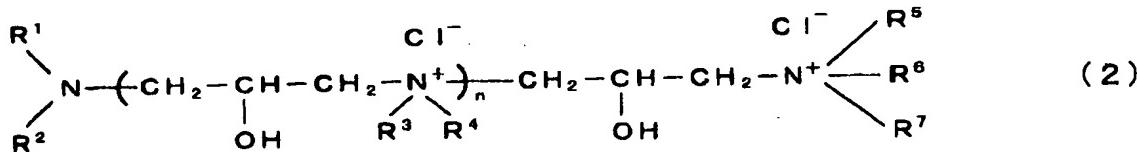
6. (Original) A copper-clad laminated board produced using the electrolytic copper foil according to Claim 5.

7. (New) A copper electrolytic solution for producing an electrolytic copper foil, said solution comprising:

(A) a quaternary amine salt obtained by a reaction between epichlorohydrin and an amine compound mixture composed of a secondary amine compound and a tertiary amine compound; and

(B) an organic sulfur compound,

wherein the quaternary amine salt is expressed by the following General Formula (2):



and, in General Formula (2), R<sup>1</sup>, R<sup>2</sup>, R<sup>3</sup>, R<sup>4</sup>, R<sup>5</sup>, R<sup>6</sup> and R<sup>7</sup> are each a methyl group or an ethyl group and n is a number from 1 to 1000.

8. (New) The electrolytic copper foil according to Claim 5, wherein the electrolytic copper foil has a surface roughness Rz of 0.93 to 1.78 µm, an ordinary-temperature elongation of 3.10 to 10.34%, an ordinary-temperature tensile strength of 31.0 to 76.5 kgf/mm<sup>2</sup>, a high-temperature elongation of 8.8 to 18.5%, and a high-temperature tensile strength of 20.0 to 23.0 kgf/mm<sup>2</sup>.